

Microwave Ceramics and Modules

4-Pole Filter XM Radio

Design Goal



Features

- SMD filter consisting of coupled resonators with stepped impedances
- MgTiO₃ CaTiO₃ ($\varepsilon_r = 21/TC_f = 0 \pm 10$ ppm/K) with a coating of copper (10µm) and tin (>5µm)
- Excellent reflow solderability, no migration effect due to copper/tin metallization
- ESD insensitivity and ESD protecting due to filter characteristics

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Filter F4052



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Design Goal

Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint



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Characteristics

			min.	typ.	max.	
Center frequency		f _C	-	2338.755	-	MHz
Insertion loss		αIΓ		2.2	2.5	dB
Passband		В	5.5			MHz
Amplitude ripple (peak - peak)		$\Delta \alpha$		0.2	0.5	dB
Standing wave ratio		SWR		1.4	2.0	
Group delay in Passband				15	40	
Impedance		Z		50		Ω
Attenuation	at 2198.755 (f _c –140MHz) at 2478.755 (f _c +140MHz)	α	45 50	49 54		dB dB

Maximum ratings

EC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	$ au_{op}$	-20 / +80	°C

Typical passband characteristic



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Processing information

• Wettability acc. to IEC 68-2-58: \geq 75% (after aging)

Soldering Requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	℃ ℃

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, polyester, grey
- Pieces/tape: t.b.d.

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